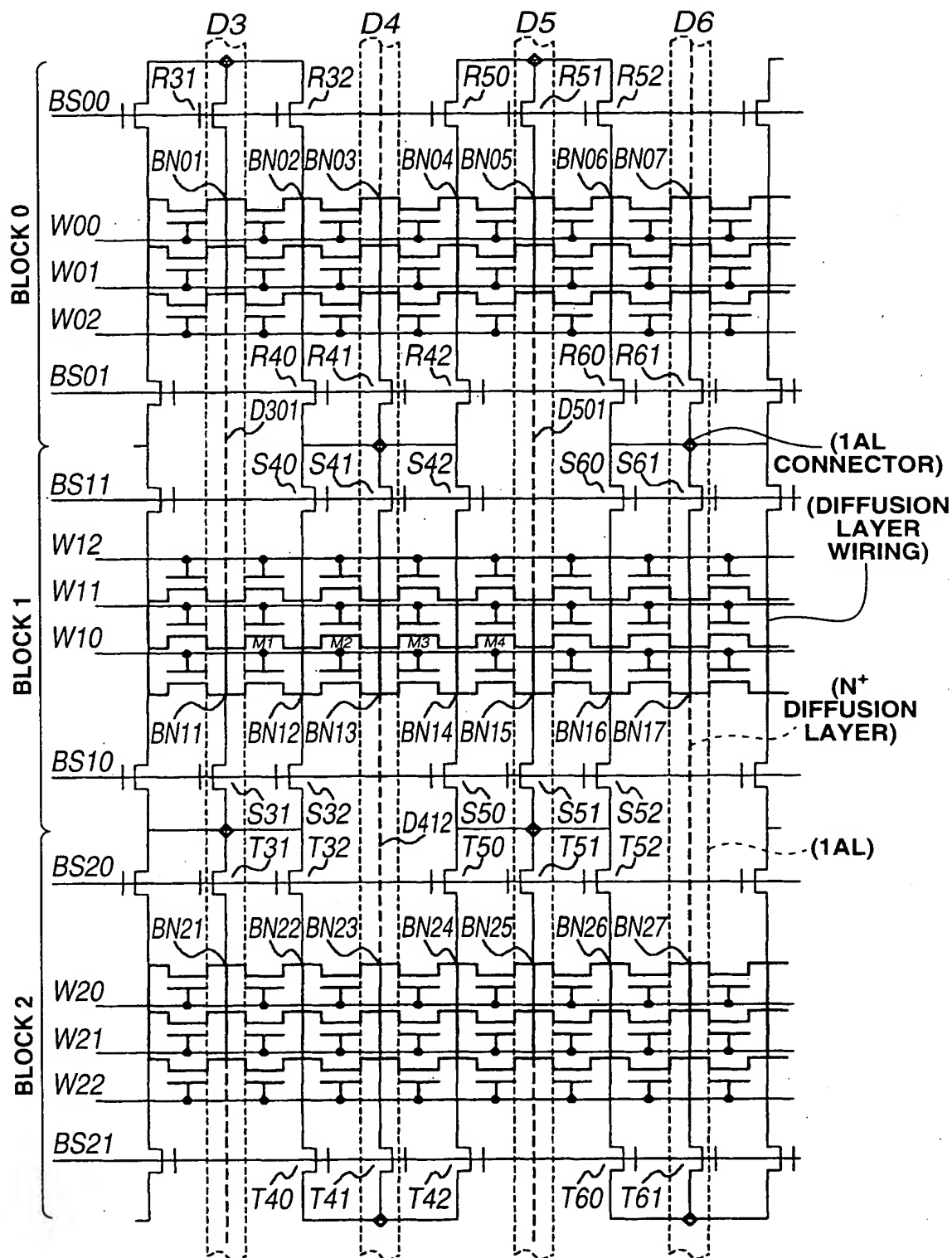


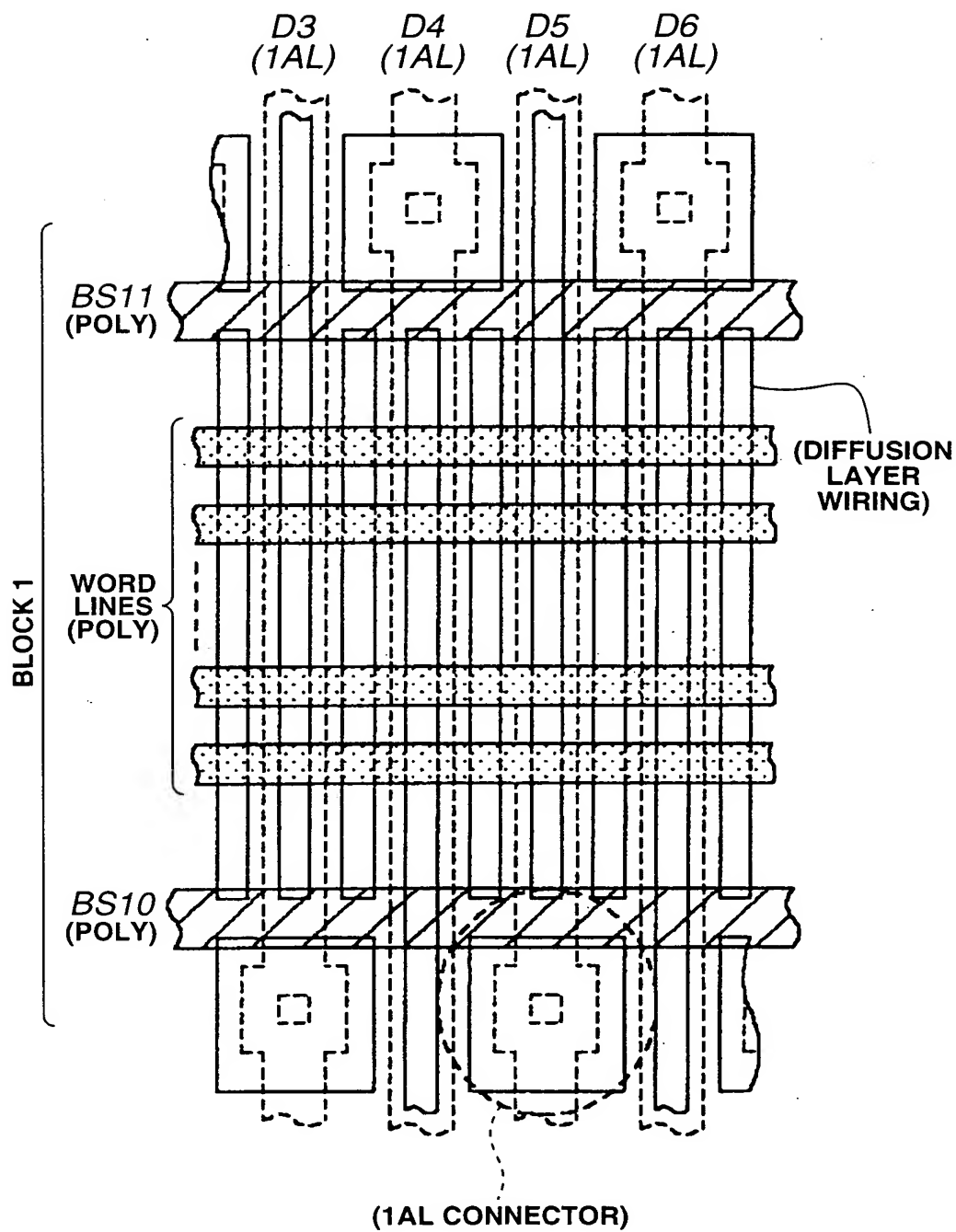


FIG.1



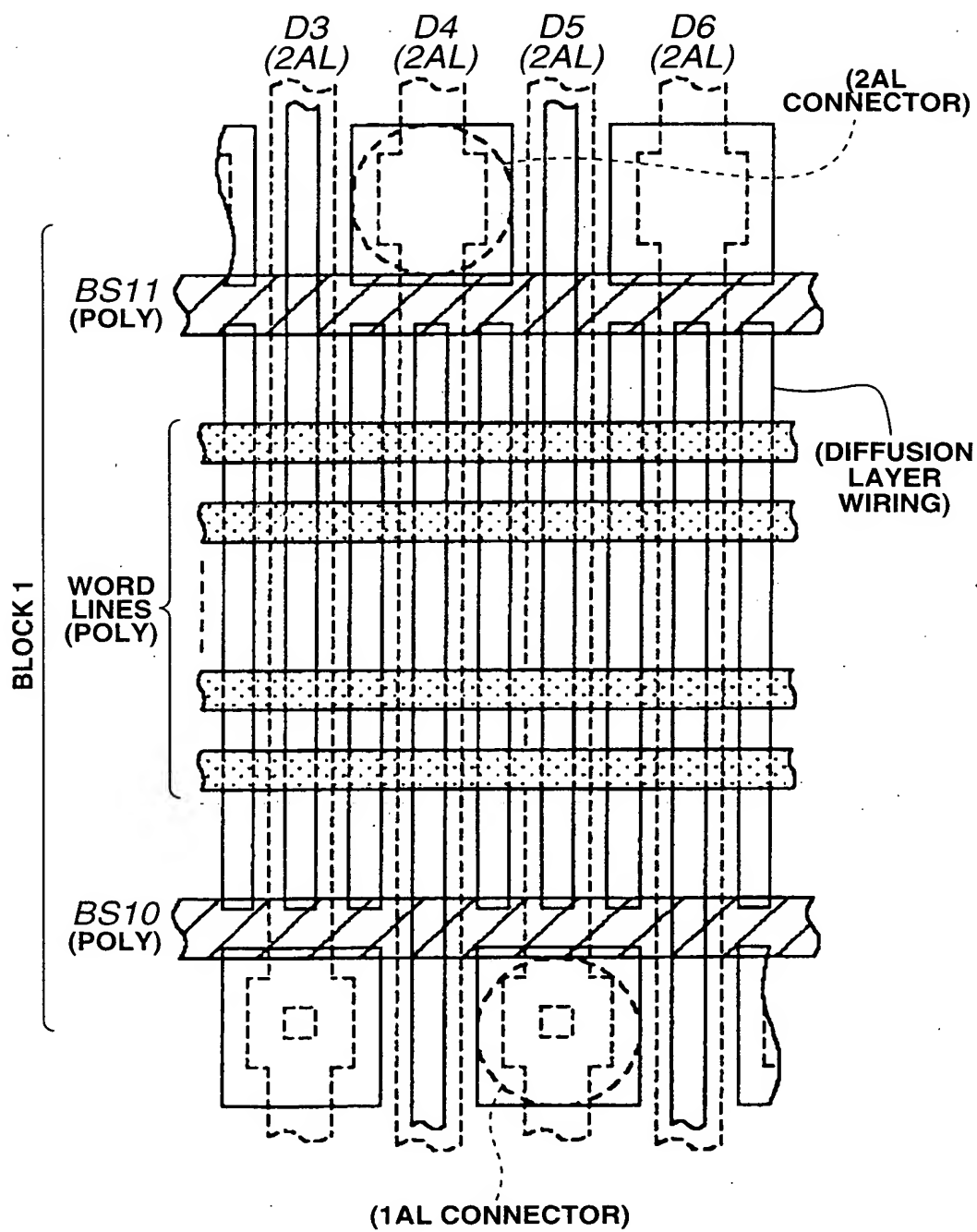
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FIG.2



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FIG.3



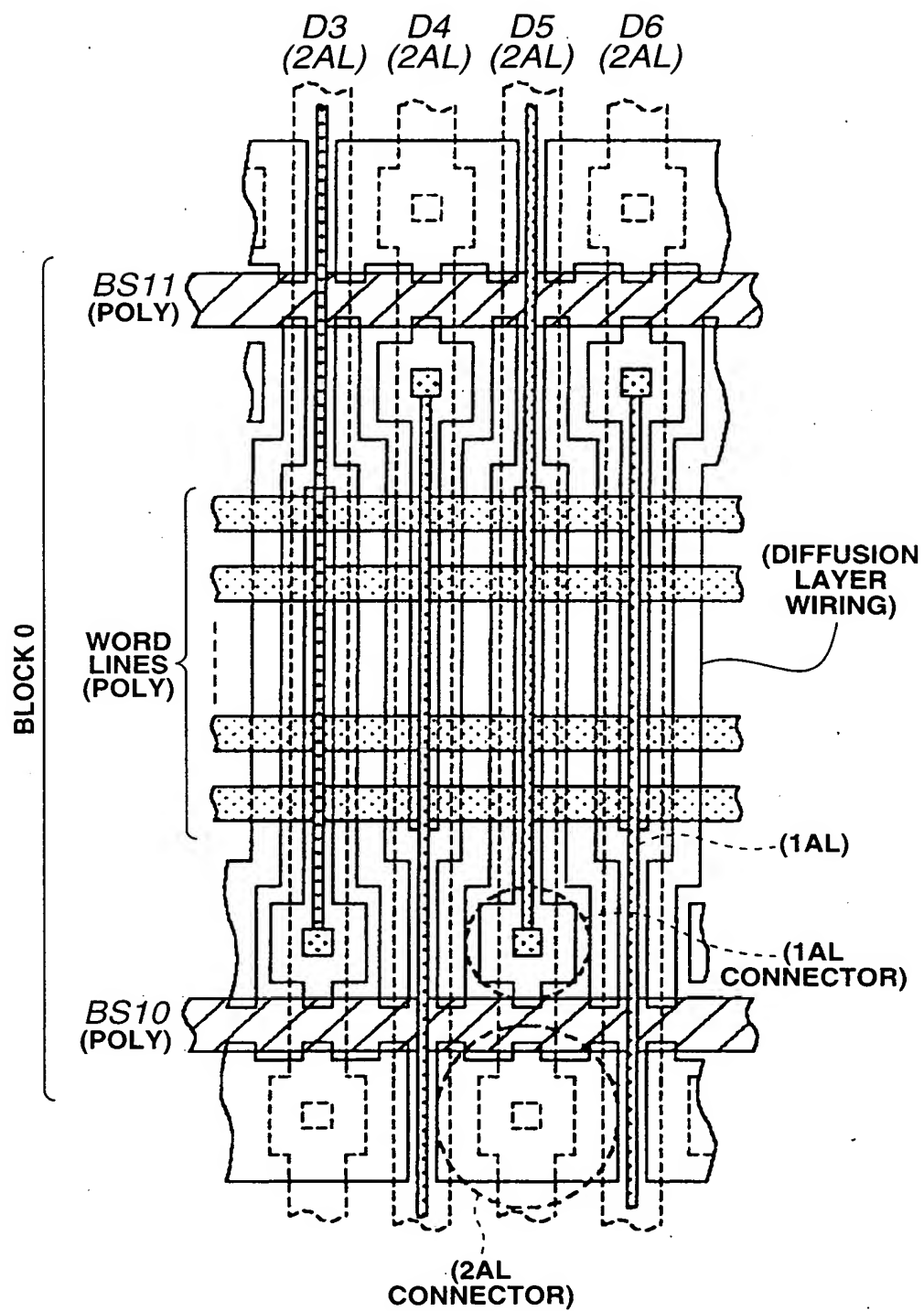
The diagram illustrates a complex semiconductor layout divided into three main blocks: BLOCK 0, BLOCK 1, and BLOCK 2. Each block contains a grid of horizontal and vertical lines representing wiring and various electronic components.

- BLOCK 0:** Contains components labeled BS00, BS01, BS11, BS10, BS20, BS21, W00, W01, W02, W12, W11, W10, W20, W21, W22, and various resistors (R31, R32, R40, R41, R42, R50, R51, R52, R60, R61) and capacitors (BN01, BN02, BN03, BN04, BN05, BN06, BN07, BN11, BN12, BN13, BN14, BN15, BN16, BN17, BN21, BN22, BN23, BN24, BN25, BN26, BN27). It also shows diffusion layer wiring and connectors (1AL, 2AL).
- BLOCK 1:** Contains components labeled BS11, BS10, BS20, BS21, W12, W11, W10, W20, W21, W22, and various resistors (R40, R41, R42, R50, R51, R52, R60, R61) and capacitors (BN11, BN12, BN13, BN14, BN15, BN16, BN17, BN21, BN22, BN23, BN24, BN25, BN26, BN27). It also shows diffusion layer wiring and connectors (1AL, 2AL).
- BLOCK 2:** Contains components labeled BS20, BS21, W20, W21, W22, and various resistors (R40, R41, R42, R50, R51, R52, R60, R61) and capacitors (BN21, BN22, BN23, BN24, BN25, BN26, BN27). It also shows diffusion layer wiring and connectors (1AL, 2AL).

The diagram uses a variety of symbols and labels to represent different components and their connections, providing a comprehensive view of the device's internal structure.

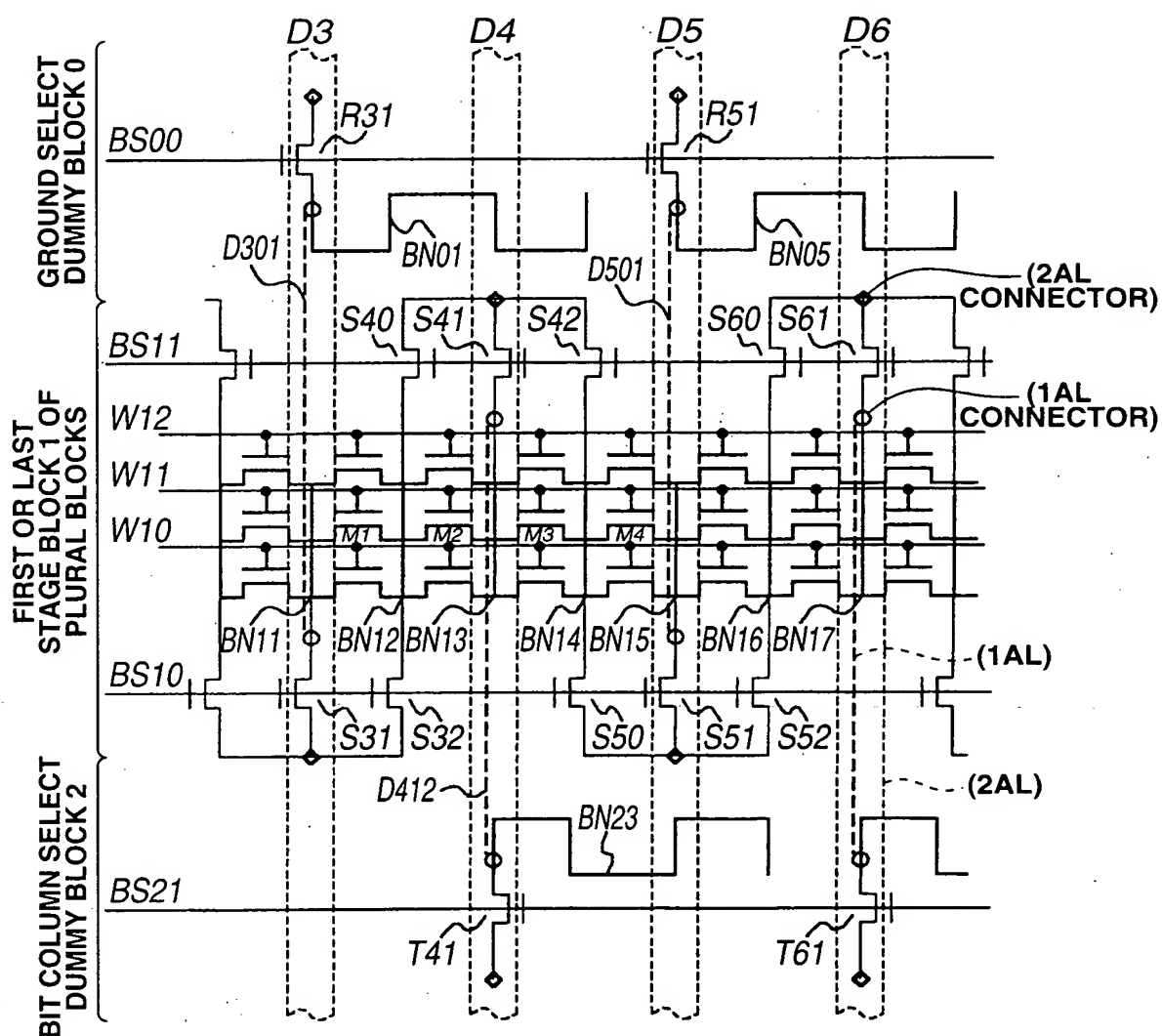
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FIG.5



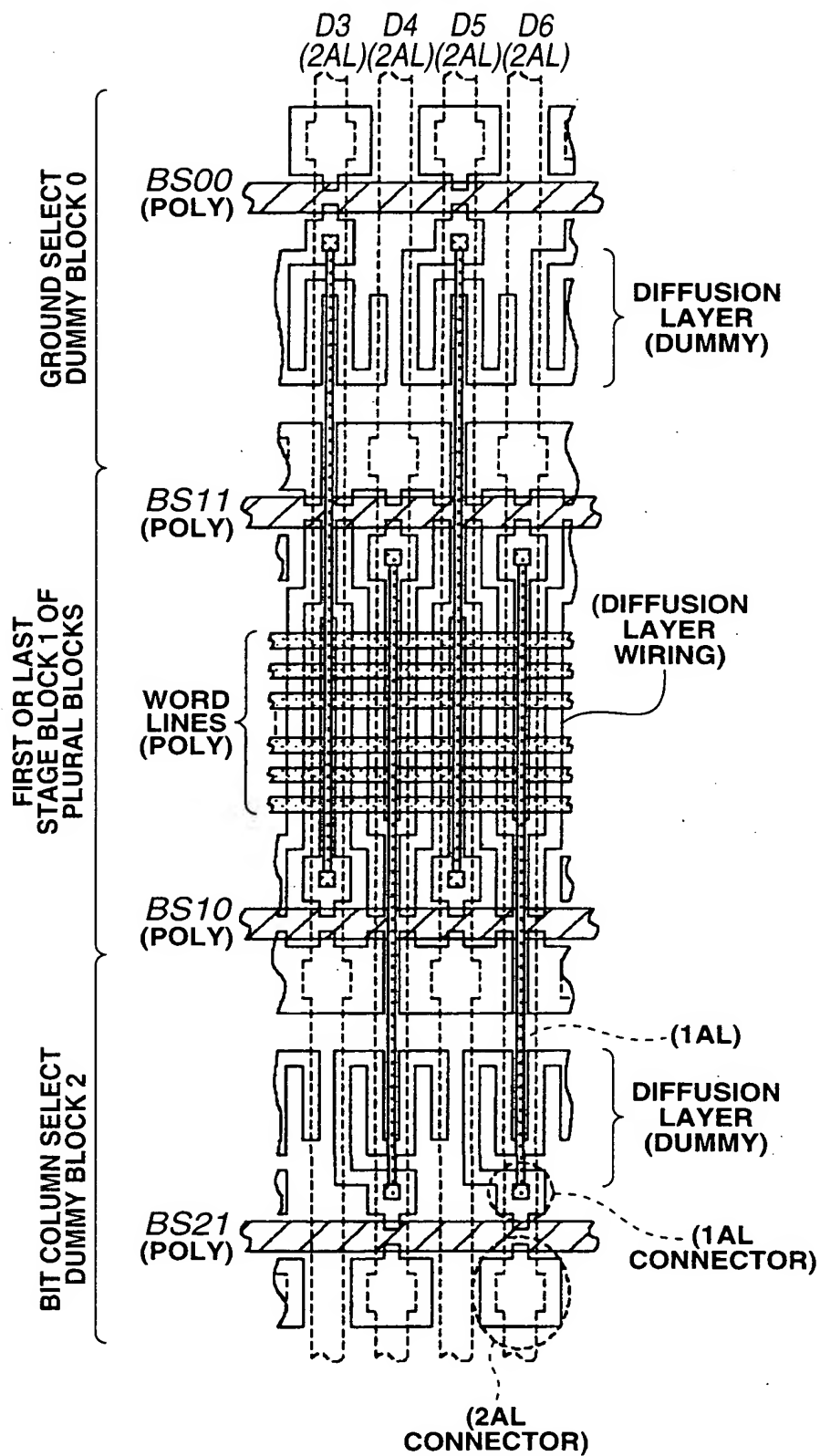
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FIG.6

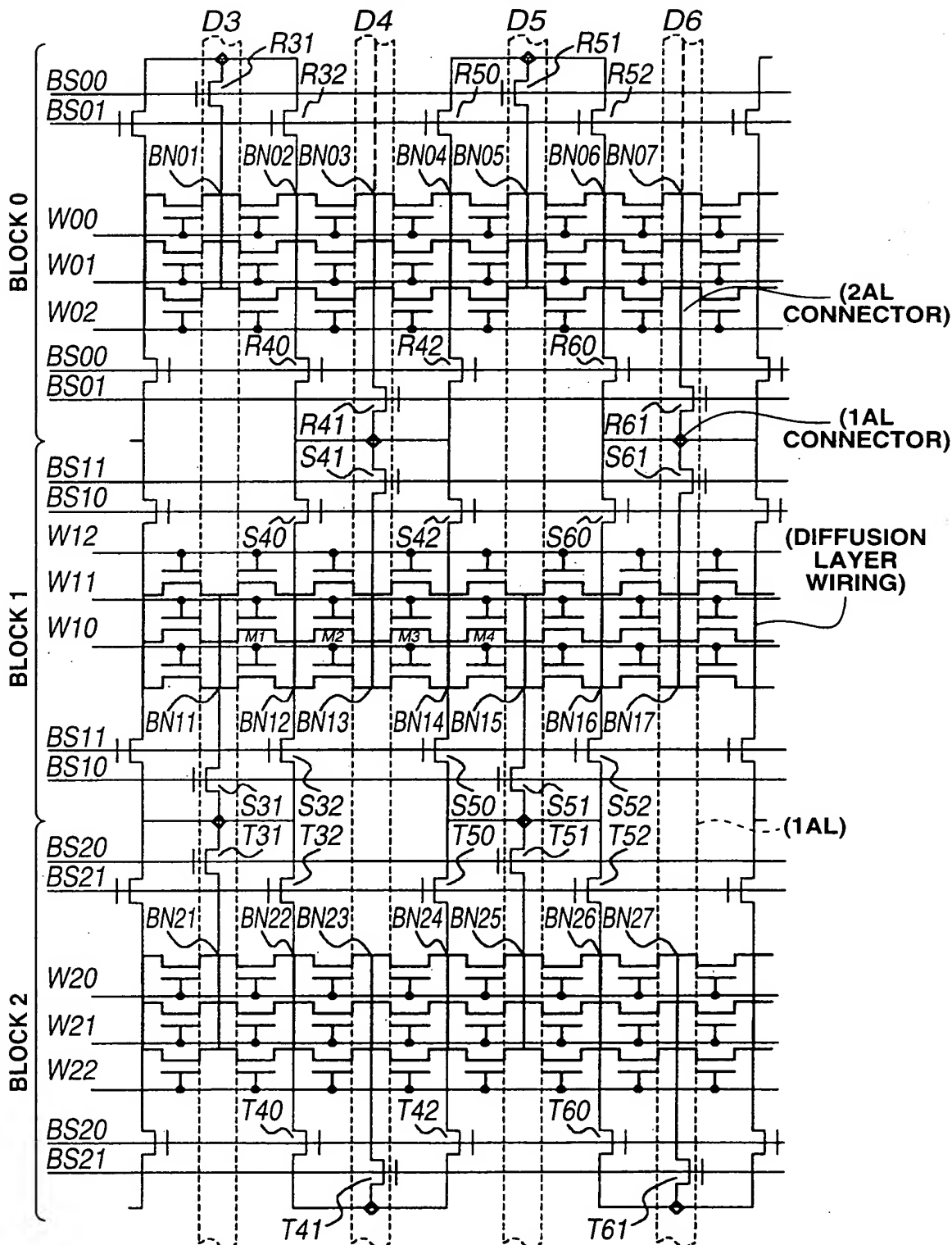


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FIG. 7

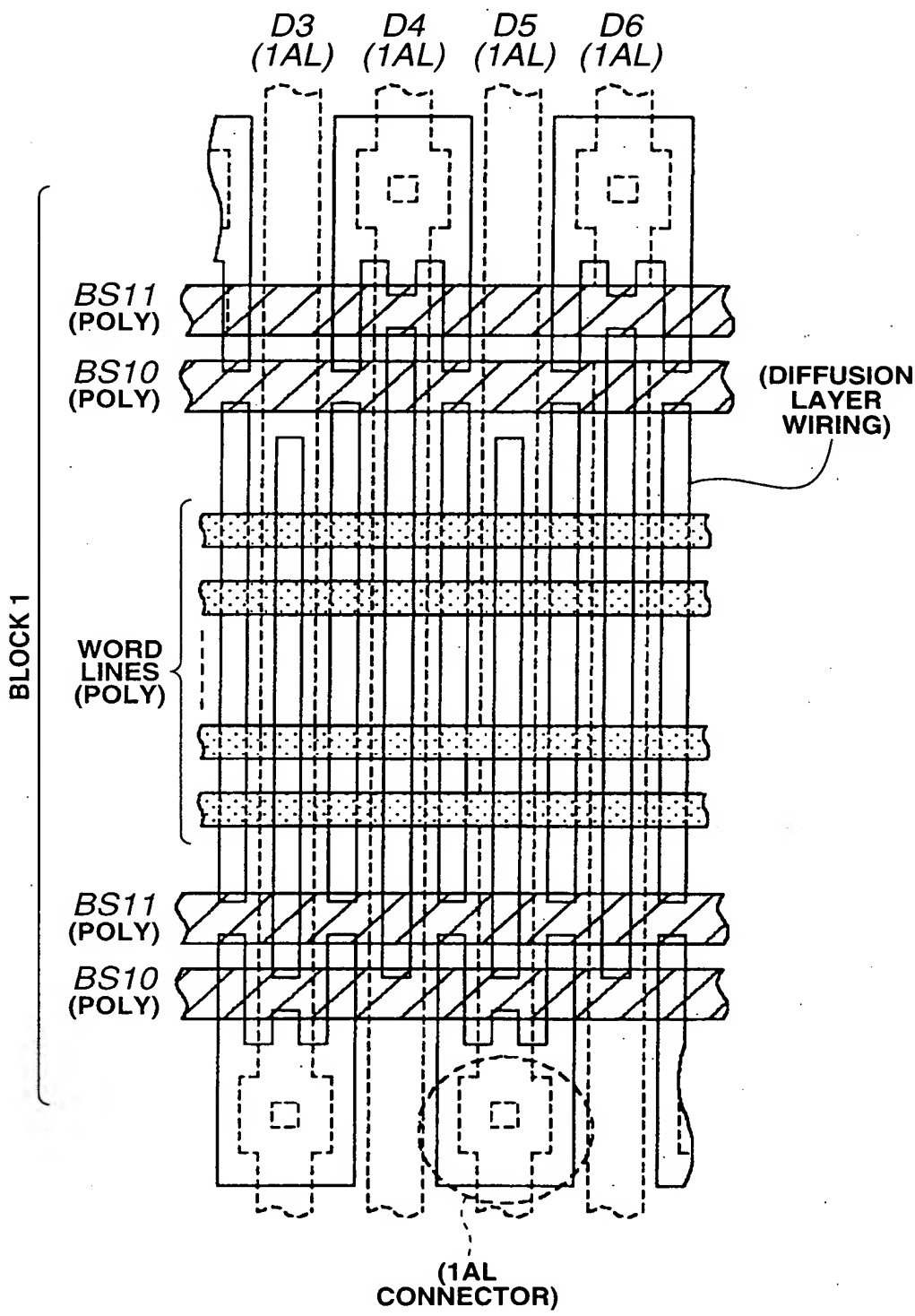


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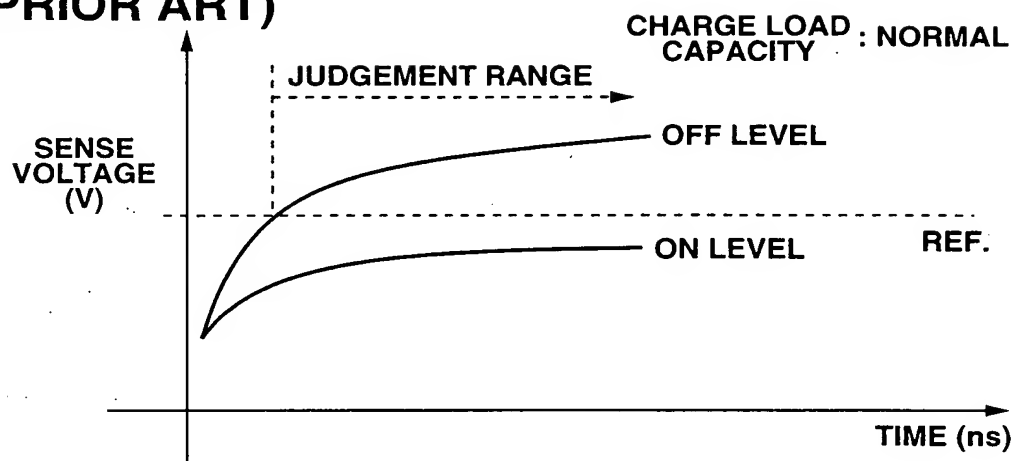
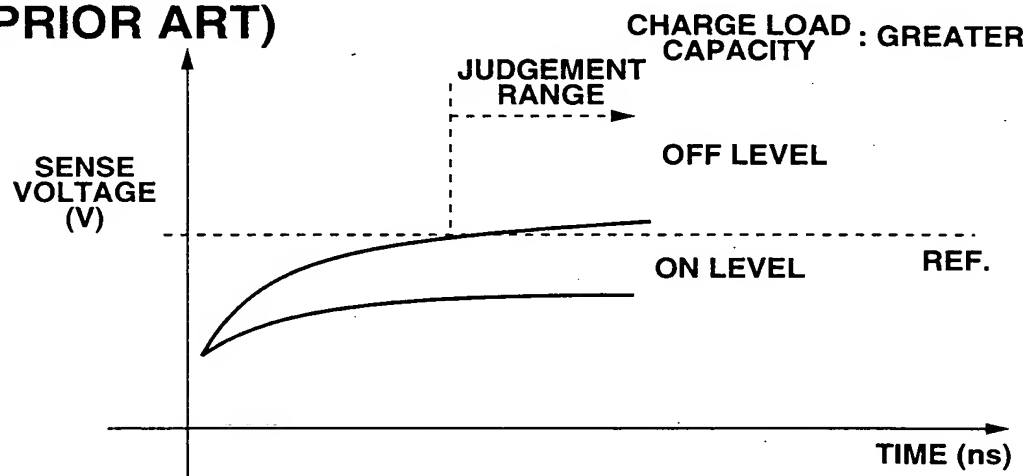
**FIG.8**  
**(PRIOR ART)**



**FIG.9**  
**(PRIOR ART)**



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**FIG.10A**  
(PRIOR ART)**FIG.10B**  
(PRIOR ART)**FIG.10C**  
(PRIOR ART)